No.	AEC-Q200 Test Item		Specifications	AEC-	Q200 Test Method	
1	Pre- and P	Post-Stress Test		-		
2	High Temperature Exposure (Storage)		The measured and observed characteristics should satisfy the specifications in the following table.			
		Appearance	No marking defects	Set the capacitor for 1000±12 hours at 150±3°C. Let sit for 24±2 hours at room temperature, then measure.		
		Capacitance Change	Within ±10%			
		D.F.	0.05 max.			
		I.R.	More than 10,000M Ω or 100M Ω \cdot μ F (Whichever is smaller)			
	Temperature Cycle		The measured and observed characteristics should satisfy the specifications in the following table.	Fix the capacitor to the supporting jig in the same manner and under the same conditions as (19). Perform the 1000 cycles		
		Appearance	No marking defects	according to the 4 heat treatments listed in the following table. Let sit for 24±2 hours at room temperature, then measure. Step 1 2 3 4 Temp. (°C) -55+0/-3 Room Temp. 125+3/-0 Room Temp. Time (min.) 15±3 1 15±3 1		
3		Capacitance Change	Within ±10%		2 3 4	
		D.F.	0.025 max.		1 15±3 1	
		I.R.	More than 10,000M Ω or 100M Ω · μ F (Whichever is smaller)	Perform the heat treatment at 150+0/-10°C for 60±5 minutes and then let sit for 24±2 hours at room temperature. Per EIA-469 Apply the 24-hour heat (25 to 65°C) and humidity (80 to 98% treatment shown below, 10 consecutive times.		
4	Destructi Physical		No defects or abnormalities			
	Moisture Resistance		The measured and observed characteristics should satisfy the specifications in the following table.			
		Appearance	No marking defects	Let sit for 24±2 hours at room temperature, then meas	oom temperature, then measure.	
		Capacitance Change	Within ±12.5%		umidity Humidity Humidity Humidity 0-98% 80-98% 90-98% 80-98% 90-98%	
		D.F.	0.05 max.	0 55 40 40 40 40 40 40 40 40 40 40 40 40 40		
5		I.R.	More than 10,000M Ω or 100M $\Omega \cdot \mu F$ (Whichever is smaller)		One cycle = 24 hours 5 7 8 9 101112131415161718192021222324	
	Biased Humidity		The measured and observed characteristics should satisfy the specifications in the following table.	Apply the rated voltage and DC1.3+0.2/-0V (add $6.8k\Omega$		
		Appearance	No marking defects	resistor) at 85±3°C and 80 to 85% humidity for 1000±12 hours. Remove and let sit for 24±2 hours at room temperature, then measure. The charge/discharge current is less than 50mA.		
6		Capacitance Change	Within ±12.5%			
		D.F.	0.05 max.	Pretreatment Perform the heat treatm	ent at 150+0/-10°C for 60±5 minutes	
		I.R.	More than 1,000M Ω or 10M Ω · μ F (Whichever is smaller)	1	hours at room temperature.	
	Operational Life		The measured and observed characteristics should satisfy the specifications in the following table.	Apply voltage as in the Table for 1000±12 hours at 125±3°C. Let sit for 24±2 hours at room temperature, then measure.		
		Appearance	No marking defects	The charge/discharge current is less than 50mA.		
7	-	Capacitance Change	Within ±12.5%	DC250V 150% of the rated voltage DC630V 120% of the rated voltage •Pretreatment	-	
		D.F.	0.05 max.			
	I.R.		More than 1,000M Ω or 10M Ω \cdot μ F (Whichever is smaller)	Apply test voltage for 60±5 minutes at test temperature. Remove and let sit for 24±2 hours at room temperature.		
8	External \	Visual	No defects or abnormalities	Visual inspection		
9	Physical [Dimension	Within the specified dimensions	Using calipers and micro	meters	

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No.	o. AEC-Q200 Test Item		Specifications	AEC-Q200 Test Method		od
10		Appearance Capacitance	No marking defects	Per MIL-STD-202 Method 215 Solvent 1: 1 part (by volume) of isopropyl alcohol 3 parts (by volume) of mineral spirits Solvent 2: Terpene defluxer Solvent 3: 42 parts (by volume) of water 1 part (by volume) of propylene glycol monomethyl ether 1 part (by volume) of monoethanolamine		
	Resistance to Solvents	Change D.F.	Within the specified tolerance 0.025 max.			spirits
	to solvents	I.R.	More than 10,000M Ω or 100M Ω · μF (Whichever is smaller)			
11		Appearance	No marking defects			
	Mechanical Shock	Capacitance Change	Within the specified tolerance	Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks The specified test pulse should be Half-sine and should have duration: 0.5ms, peak value: 1500g and velocity change: 4.7n	ecimen (18 shocks). ne and should have a	
		D.F.	0.025 max.		elocity change: 4.7m/s.	
		Appearance	No defects or abnormalities	Solder the capacitor to the test jig (glass epoxy board) in the same manner and under the same conditions as (19). The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied		
		Capacitance Change	Within the specified tolerance			
12	Vibration	D.F.	0.025 max.	having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 2000Hz. The frequency range, from 10 to 2000Hz and return to 10Hz, should be traversed in approximately 20 minutes. This motion should applied for 12 items in each 3 mutually perpendicular direction (total of 36 times).		
	Resistand Soldering		The measured and observed characteristics should satisfy the specifications in the following table.	Immerse the conscitor in a subsetic colder colution at 2001 F20		
		Appearance	No marking defects	•	Immerse the capacitor in a eutectic solder solution at 260±5°C 10±1 seconds. Let sit at room temperature for 24±2 hours, the	
13		Capacitance Change	Within ±10%	measure. •Pretreatment		
		D.F.	0.025 max.	Perform the heat treatment at 150+0/-10°C for 60±5 minutes and then let sit for 24±2 hours at room temperature.		
		I.R.	More than 10,000M Ω or 100M $\Omega \cdot \mu F$ (Whichever is smaller)			,
	Thermal Shock		The measured and observed characteristics should satisfy the specifications in the following table.	Fix the capacitor to the supporting jig in the same manner ar under the same conditions as (19). Perform the 300 cycles		m the 300 cycles
		Appearance	No marking defects	 according to the two heat treatments listed in the following to (maximum transfer time is 20 seconds). Let sit for 24±2 hour room temperature, then measure. 		_
		Capacitance	Within ±10%			
14		Change		Step (°C)	1 -55+0/-3	2 125+3/-0
		D.F.	0.025 max.	Temp. (°C) Time (min.)	-55+0/-3 15±3	125+3/-0 15±3
		I.R.	More than 10,000M Ω or 100M $\Omega \cdot \mu F$ (Whichever is smaller)	Pretreatment Perform the heat treatment at 150+0/-10°C for 60±5 minute and then let sit for 24±2 hours at room temperature.		°C for 60±5 minutes
		Appearance	No marking defects	Per AEC-Q200-002		
15	ESD	Capacitance Change	Within the specified tolerance			
13		D.F.	0.025 max.	1 61 AEG-0200-002		
		I.R.	More than 10,000M Ω or 100M $\Omega \cdot \mu F$ (Whichever is smaller)			
	Solderability		derability 95% of the terminations are to be soldered evenly and continuously.	 (a) Preheat at 155°C for 4 hours. After preheating, immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-902) (25% rosin in weight proportion). Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5°C. (b) Should be placed into steam aging for 8 hours±15 minutes. After preheating, immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5°C. 		
16						
				(c) Should be placed into steam aging for 8 hours±15 minutes. After preheating, immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in eutectic solder solution for 120 ±5 seconds at 260±5°C.		

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No.		·Q200 Item	Specifications	AEC-Q200 Test Method		
		Appearance	No defects or abnormalities	Visual inspection.		
		Capacitance Change	Within the specified tolerance	The capacitance/Q should be measured at 25°C at the frequent and voltage shown in the table.		
		D.F.	0.025 max.	Capacitance Frequency Voltage C<1000pF		
17	Electrical Characteri- zation	I.R.	25°C More than 10,000M Ω or 100M $\Omega \cdot \mu$ F (Whichever is smaller) Max. Operating Temperature125°C More than 1,000M Ω or 10M $\Omega \cdot \mu$ F (Whichever is smaller)	The insulation resistance should be measured with DC500±50V (DC250±25V in case of rated voltage: DC250V) at 25°C and 125°C and within 2 minutes of charging.		
		Dielectric Strength	No failure	No failure should be observed when voltage as in the Table is applied between the terminations for 1 to 5 seconds, provided the charge/discharge current is less than 50mA. Rated Voltage Test Voltage DC250V 200% of the rated voltage DC630V 150% of the rated voltage		
		Appearance	No marking defects	Solder the capacitor on the test jig (glass epoxy board) as		
18		Capacitance Change	Within ±12.5%	shown in Fig. 1 using a eutectic solder. Then apply a force in the direction shown in Fig. 2 for 5±1 seconds. The soldering should be done by the reflow method and should be conducted with		
	Board Flex		t 1.6mm	GCJ21 0.8 3.0 1.3 GCJ31 2.0 4.4 1.7 GCJ32 2.0 4.4 2.6 GCJ43 3.0 6.0 3.3 GCJ55 4.2 7.2 5.1 (in mm) Pressurizing speed: 1.0mm/s Pressurize Capacitance meter 45 Fig. 2		
		Appearance	No marking defects	Solder the capacitor to the test jig (glass epoxy board) as		
	Terminal Strength	Capacitance Change	Within the specified tolerance	shown in Fig. 3 using a eutectic solder. Then apply 18N force in parallel with the test jig for 60 seconds. The soldering should be done by the reflow method and should		
		D.F.	0.025 max.	be conducted with care so that the soldering is uniform and free of defects such as heat shock.		
19				Type a b c GCJ21 1.2 4.0 1.65 GCJ31 2.2 5.0 2.0 GCJ32 2.2 5.0 2.9 GCJ43 3.5 7.0 3.7 GCJ55 4.5 8.0 5.6		
		I.R.	More than 10,000M Ω or 100M Ω \cdot μ F (Whichever is smaller)	Solder resist Baked electrode or copper foil Fig. 3		

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No.	AEC-Q200 Test Item		Specifications	AEC-Q200 Test Method
20	Beam Load Test		The chip should endure the following force. Chip thickness < 1.25mm rank: 15N Chip thickness ≥ 1.25mm rank: 54.5N	Place the capacitor in the beam load fixture as in Fig. 4. Apply force. Fig. 4 Speed at which to supply the Stress Load: 2.5mm / s
21	Capacitance Temperature Character- istics Capac Chang	citance ge	Within ±15%	The capacitance change should be measured after 5 minutes at each specified temperature stage. Step